

AMENDMENTS TO THE CLAIMS

1 to 7. (Canceled)

8. (New) A copper-based alloy having soundness of alloy improved during a course of solidification of the copper-based alloy by crystallizing an intermetallic compound capable of solidifying within a range of solidifying temperature as a temperature region between a solidus line and a liquidus line surpassing the solidus line in dendritic gaps of the alloy, thereby suppressing migration of a solute and consequently effecting dispersion of microporosities and utilizing the crystallization of the intermetallic compound as well for effecting suppression of a low melting metal or a low melting intermetallic compound capable of solidifying at a temperature falling short of the solidifying temperature of the copper-based alloy, and relying on the low melting metal or low melting intermetallic compound to enter the microporosities and undergo dispersed crystallization and consequently suppress occurrence of microporosities.

9. (New) A copper-based alloy according to claim 8, wherein at least 5.0 to 10.0 weight% of Zn and $0 < \text{Se} \leq 1.5$ weight% of Se are contained and ZnSe is crystallized as an intermetallic compound in the dendritic gaps of the alloy during the course of solidification of the copper-based alloy.

10. (New) A copper-based alloy according to claim 8, wherein the intermetallic compound has a surface ratio of 0.3% or more and 5.0% or less.

11. (New) A copper-based alloy according to claim 8, wherein at least 0.25 to 3.0 weight% of Bi is contained and Bi is crystallized as the low melting metal in a region of the solute during the course of solidification of the copper-based alloy.

12. (New) A copper-based alloy according to claim 8, wherein the low melting metal or low melting intermetallic compound has a surface ratio of 0.2% or more and 2.5% or less.

13. (New) A copper-based alloy according to claim 8, comprising at least 5.0 to 10.0

weight% of Zn, 2.8 to 5.0 weight% of Sn, 0.25 to 3.0 weight% of Bi, $0 < \text{Se} \leq 1.5$ weight% of Se, less than 0.5 weight% of P, the balance of Cu, and less than 0.2 weight% of Pb as an unavoidable impurity.

14. (New) An ingot using the copper-based alloy according claim 8 or a liquid-contacting part having the copper-based alloy mechanically formed.